# 504550199 09/15/2017

# PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1 Stylesheet Version v1.2 EPAS ID: PAT4596907

SUBMISSION TYPE:	NEW ASSIGNMENT	
NATURE OF CONVEYANCE:	ASSIGNMENT	

#### **CONVEYING PARTY DATA**

Name	Execution Date	
DR. MEIK PANITZ	06/21/2017	

#### **RECEIVING PARTY DATA**

Name:	JENOPTIK OPTICAL SYSTEMS GMBH	
Street Address: GOESCHWITZER STRASSE 25		
City: JENA		
State/Country:	GERMANY	
Postal Code:	07745	

#### **PROPERTY NUMBERS Total: 1**

Property Type	Number
Application Number:	15558859

#### **CORRESPONDENCE DATA**

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ATTORNEY DOCKET NUMBER:	Y2954-00095	
NAME OF SUBMITTER:	ARTHUR M. DRESNER	
SIGNATURE:	/arthur m dresner/	
DATE SIGNED:	09/15/2017	

### **Total Attachments: 2**

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PATENT 504550199 REEL: 043604 FRAME: 0469

#### ASSIGNMENT

WHEREAS, I, PANITZ, Meik, Dr., a citizen of Germany, residing at Graben 10, Weimar, Germany 99423, ASSIGNOR, is the inventor of the invention in

# METHOD AND DEVICE FOR SEVERING A MICROCHIP FROM A WAFER AND ARRANGING THE MICROCHIP ON A SUBSTRATE

Ø	which is identified by Duane Morris LLP Docket No. Y2954-00095	
	which was filed on, as Application No	

for which I have executed an application for a Patent of the United States

and WHEREAS, JENOPTIK Optical Systems GmbH, Assignee, having a place of business at Goeschwitzer Strasse 25, 07745 Jena, Germany, is desirous of obtaining my entire right, title and interest in, to and under the said invention and the said application:

NOW, THEREFORE, in consideration of the sum of One Dollar (\$1.00) to me in hand paid, and other good and valuable consideration, the receipt of which is hereby acknowledged, I, the said ASSIGNOR, have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said ASSIGNEE, its successors, legal representatives and assigns, my entire right, title and interest in, to and under the said invention, and the said United States application and all divisions, renewals and continuations thereof, and all Patents of the United States which may be granted thereon and all reissues and extensions thereof; and all applications for industrial property protection, including, without limitation, all applications for patents, utility models, and designs which may hereafter be filed for said invention in any country or countries foreign to the United States, together with the right to file such applications and the right to claim for the same the priority rights derived from said United States application under the Patent Laws of the United States, the International Convention for the Protection of Industrial Property, or any other international agreement or the domestic laws of the country in which any such application is filed, as may be applicable; and all forms of industrial property protection, including, without limitation, patents, utility models, inventors' certificates and designs which may be granted for said invention in any country or countries foreign to the United States and all extensions, renewals and reissues thereof;

AND I HEREBY authorize and request the Commissioner for Patents and any Official of any country or countries foreign to the United States, whose duty it is to issue patents or other evidence or forms of industrial property protection on applications as aforesaid, to issue the same to the said ASSIGNEE, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

AND I HEREBY covenant and agree that I have full right to convey the entire interest herein assigned, and that I have not executed, and will not execute, any agreement in conflict herewith.

AND I HEREBY further covenant and agree that I will communicate to the said ASSIGNEE, its successors, legal representatives and assigns, any facts known to me respecting said invention, and testify in any legal proceeding, sign all lawful papers, execute all divisional, continuing, reissue and foreign applications, make all rightful oaths, and generally do everything possible to aid the said ASSIGNEE, its successors, legal representatives and assigns, to obtain and enforce proper protection for said invention in all countries.

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Date:	June, 21	, 2017	DR. MEIK PANITZ	L.S.
	WITNESS:		DR. MEIR PAINIL	
	Reinhard Meiss	ine/		
	(Printed Name)			
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